

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5331015

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SUNEDISON SEMICONDUCTOR LIMITED	06/06/2018
MEMC JAPAN LTD	06/06/2018
MEMC ELECTRONIC MATERIALS S.P.A.	06/06/2018
RECEIVING PARTY DATA	
Name:	GLOBALWAFERS CO., LTD.
Street Address:	NO. 8. INDUSTRIAL EAST ROAD
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	R.O.C.
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15984586
CORRESPONDENCE DATA	
Fax Number:	(314)612-2307
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	3146215070
Email:	uspatents@armstrongteasdale.com
Correspondent Name:	RICHARD A. SCHUTH
Address Line 1:	ARMSTRONG TEASDALE LLP
Address Line 2:	7700 FORSYTH BLVD., SUITE 1800
Address Line 4:	ST. LOUIS, MISSOURI 63105
ATTORNEY DOCKET NUMBER:	28744-4872 (140039.6)
NAME OF SUBMITTER:	RICHARD A. SCHUTH
SIGNATURE:	/Richard A. Schuth/
DATE SIGNED:	01/17/2019
Total Attachments: 7	
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ASSIGNMENT

This Assignment is made by and among SunEdison Semiconductor Limited, a company organized and existing under the laws of Singapore (“SSL”), MEMC Japan Limited, a company organized and existing under the laws of Japan (“MEMC Japan”), and MEMC Electronic Materials, S.P.A., a company organized and existing under the laws of Italy (“MEMC EM”, and collectively with SSL and MEMC Japan, the “Assignors”), and GlobalWafers Co., Ltd., a company organized and existing under the laws of Taiwan and having its registered address at No. 8. Industrial East Road, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C. (hereinafter referred to as “Assignee”);

WHEREAS, on December 31, 2016, Assignors entered into certain IP Transfer Agreements with Assignee;

WHEREAS, the parties hereto desire to memorialize, *nunc pro tunc*, the assignment and ownership of all Assigned IP (defined below) for, among other things, recordal purposes with certain patent administration bodies, such as the United States Patent and Trademark Office; and

WHEREAS, Assignors acknowledge that payment in full from Assignee for all Assigned IP has heretofore been paid.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors have agreed to and do hereby sell, assign and transfer, and confirm the sale, assignment and transfer, unto Assignee all of their rights, title and interest throughout the world, including without limitation, the right to sue and recover for any past infringements, in and to the Listed IP, any other applications (including provisional, non-provisional, divisional, continuing, or reissue applications) based in whole or in part on any Listed IP, any corresponding patent or patent applications filed in any country based in whole or in part on, and/or claiming priority from, any Listed IP, any patents (including extensions thereof) of any country based in whole or in part on, and/or claiming priority from, any Listed IP, and all of the inventions described in the Listed IP and all of the aforementioned patents and patent applications (all of the foregoing, collectively, the “Assigned IP”);

TO BE HELD AND ENJOYED by said Assignee, its successors and assigns, as fully and entirely as the Assigned IP would have been held and enjoyed by Assignors had no assignment of said interest been made.

EACH ASSIGNOR hereby agrees that it will do, execute and deliver, or will cause to be done, executed and delivered, all such further lawful acts, transfers, assignments and conveyances, powers of attorney and assurances for the better assuring, conveying and confirming unto Assignee, all of such Assignor's rights, title and interest in and to the Assigned IP hereby transferred, assigned and conveyed, as Assignee may reasonably require.

[Signature Pages Follow]

IN WITNESS WHEREOF, the undersigned have caused these presents to be executed by their respective officers thereunto duly authorized this 6 day of June, 2018.

Assignor:

SUNEDISON SEMICONDUCTOR LIMITED

By: *Paul Markowitz*

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of SUNEDISON SEMICONDUCTOR LIMITED, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.

Erika Damiani
Notary Public


My Commission Expires:

July 20, 2018



Assignor:

MEMC JAPAN LTD

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri
COUNTY OF St. Charles

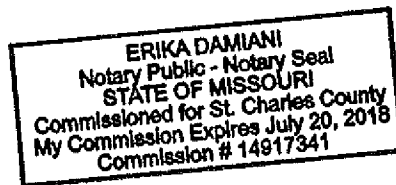
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC JAPAN LTD, known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

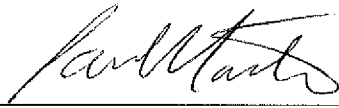
My Commission Expires:

July 20, 2018



Assignor:

MEMC ELECTRONIC MATERIALS S.P.A.

By: 


Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles)

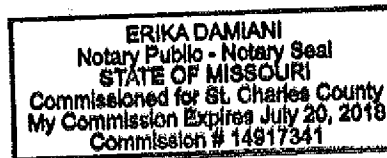
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of MEMC ELECTRONIC MATERIALS S.P.A., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

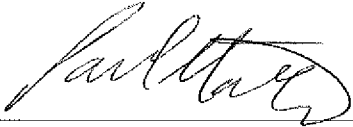
July 20, 2018



For and on behalf of GlobalWafers Co., Ltd.

Assignee:

GLOBALWAFERS CO., LTD.

By: 

Name: Paul Markowitz

Title: Director of Intellectual Property

STATE OF Missouri)
COUNTY OF St. Charles

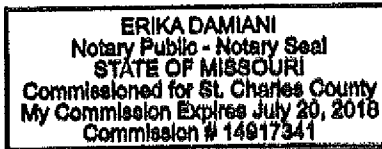
On this 6 day of June, 2018, before me, a Notary Public, personally appeared Paul Markowitz, an officer of GLOBALWAFERS CO., LTD., known to me to be the person who executed the within Assignment, and who did state that said instrument was signed on behalf of said company, and acknowledged to me that he executed the same for the purposes therein stated.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal the date and year last above written.


Notary Public

My Commission Expires:

July 20, 2018



SCHEDULE A

TITLE	Country	Application Number	Filing Date	Publication Number	Publication Date	Patent Number	Issue Date
SYSTEMS AND METHODS FOR PERFORMING EPITAXIAL SMOOTHING PROCESSES ON SEMICONDUCTOR STRUCTURES	EP	15821242.3	14-Jun-2017	3234987	25-Oct-2017		
SYSTEMS AND METHODS FOR PERFORMING EPITAXIAL SMOOTHING PROCESSES ON SEMICONDUCTOR STRUCTURES	JP	2017-532623	16-Jun-2017	2018-504777	15-Feb-2018		
SYSTEMS AND METHODS FOR PERFORMING EPITAXIAL SMOOTHING PROCESSES ON SEMICONDUCTOR STRUCTURES	CN	201580076594.7	21-Aug-2017	107251202	13-Oct-2017		
METHODS FOR PREPARING LAYERED SEMICONDUCTOR STRUCTURES AND RELATED BONDED STRUCTURES	US	15/191975	24-Jun-2016	2017-0025306	26-Jan-2017		
A METHOD OF MANUFACTURING HIGH RESISTIVITY SEMICONDUCTOR-ON-INSULATOR WAFERS WITH CHARGE TRAPPING LAYERS	TW	104137752	16-Nov-2015	201630113	16-Aug-2016		
A METHOD OF MANUFACTURING HIGH RESISTIVITY SEMICONDUCTOR-ON-INSULATOR WAFERS WITH CHARGE TRAPPING LAYERS	US	15/526798	15-May-2017	2017-0338143	23-Nov-2017		
A METHOD OF MANUFACTURING HIGH RESISTIVITY SEMICONDUCTOR-ON-INSULATOR WAFERS WITH CHARGE TRAPPING LAYERS	EP	15801599.0	2-Jun-2017	3221884	27-Sep-2017		
A METHOD OF MANUFACTURING HIGH RESISTIVITY SEMICONDUCTOR-ON-INSULATOR WAFERS WITH CHARGE TRAPPING LAYERS	JP	2017-544851	17-May-2017	2017-538297	21-Dec-2017		
METHODS AND SYSTEMS FOR POLISHING PAD CONTROL	US	15/190624	23-Jun-2016	2017-0001281	5-Jan-2017		
PREPARATION OF SILICON-GERMANIUM-ON-INSULATOR STRUCTURES	FR	1563495	31-Dec-2015	3031236	1-Jul-2016		
PREPARATION OF SILICON-GERMANIUM-ON-INSULATOR STRUCTURES	US	15/540859	29-Jun-2017	2018-0005872	4-Jan-2018		
CENTER FLEX SINGLE SIDE POLISHING HEAD HAVING RECESS AND CAP	US	14/512779	13-Oct-2014	2016-0101502	14-Apr-2016	9566687	14-Feb-2017
CENTER FLEX SINGLE SIDE POLISHING HEAD HAVING RECESS AND CAP	JP	2017-518223	4-Apr-2017	2017-530560	12-Oct-2017		

PATENT

REEL: 048051 FRAME: 0019

RECORDED: 01/17/2019